



FXN30S60T Series

Rev.A

General Description

The FXN30S60T uses advanced Silicon's MOSFET Technology, which provides high performance in on-state resistance, fast switching performance, and excellent quality.

These devices can also be utilized in industrial applications such as Low Power Drives SMPS, DC/DC converter, and general purpose applications.

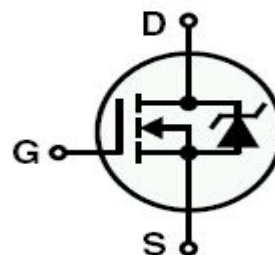
Features

- $V_{DS} = 600V$
- $ID = 30A @ V_{GS} = 10V$
- Very low on-resistance
- $R_{DS(ON)} < 0.15\Omega @ V_{GS} = 10V$
- 100% UIL Tested
- 100% Rg Tested
- 150 °C operating temperature



TO-247 Top View

N-channel



Schematic Diagram

Absolute Maximum Ratings (T_J = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	600	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current (1)	T _c =25°C(silicon limited)	I_D	30	A
	T _c =25°C(package limited)		24	
	T _c =100°C(silicon limited)		17	
Pulsed Drain Current (2)		I_{DM}	92	
Power Dissipation	T _c =25°C	PD	49	W
	T _c =100°C		47	
Single Pulse Avalanche Energy (3)		EAS	510	mJ
Junction and Storage Temperature Range		T _J , T _{stg}	-55~175	°C

Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient (1)	$R_{\theta JA}$	100	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.57	



Electrical Characteristics (T_J = 25°C)

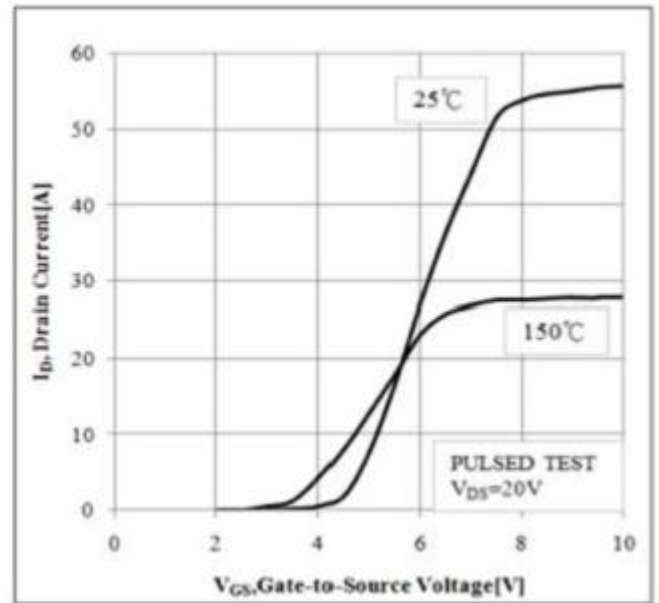
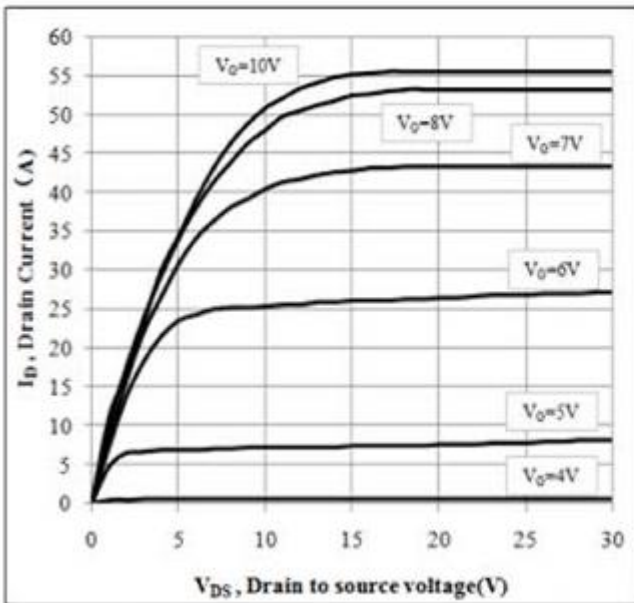
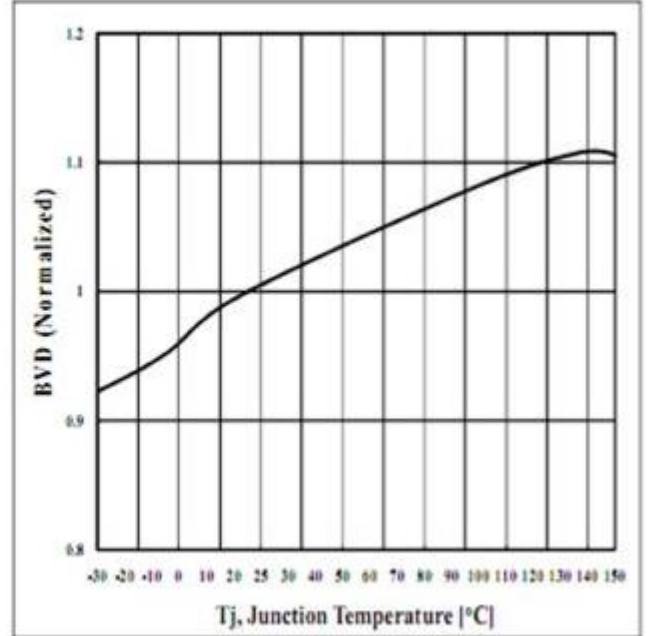
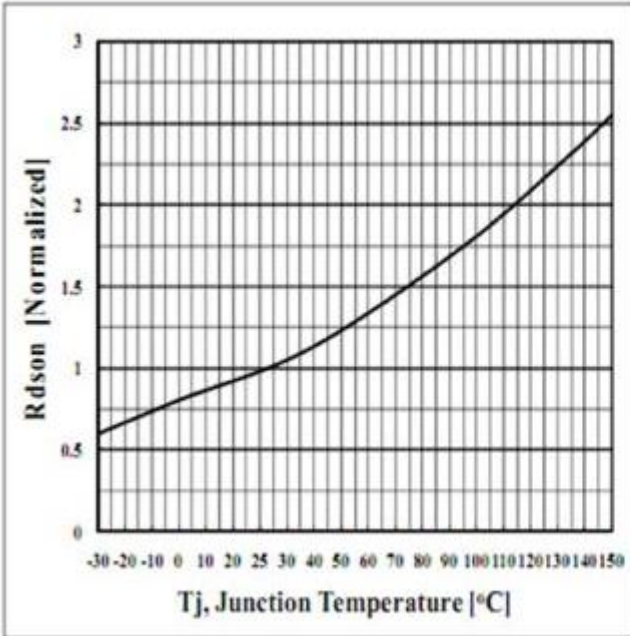
Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V	600	650	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2	3	4	
Drain Cut-Off Current	I _{DSS}	V _{DS} = 600V, V _{GS} = 0V	-	-	1	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V	-	-	±0.1	
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 12A	-	0.1	0.15	Ω
Forward Transconductance	g _{fs}	V _{DS} = 10V, I _D = 30A	-	10.5	-	S
Dynamic Characteristics						
Total Gate Charge	Q _g	V _{DS} = 520V, I _D = 15A, V _{GS} = 10V	-	49	-	nC
Gate-Source Charge	Q _{gs}		-	8.1	-	
Gate-Drain Charge	Q _{gd}		-	8.3	-	
Input Capacitance	C _{iss}	V _{DS} = 300V, V _{GS} = 0V, f = 1.0MHz	-	1966	-	pF
ReVerse Transfer Capacitance	C _{rss}		-	34	-	
Output Capacitance	C _{oss}		-	208	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DS} = 300V, I _D = 30A, R _G = 25Ω	-	16	-	ns
Rise Time	t _r		-	78	-	
Turn-Off Delay Time	t _{d(off)}		-	59	-	
Fall Time	t _f		-	57.6	-	
Gate Resistance	R _g	f = 1 MHz	-	2.5	-	Ω
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	V _{SD}	I _S = 30A, V _{GS} = 0V	-	0.9	1.2	V
Body Diode ReVerse RecoVery Time	t _{rr}	I _F = 30A, di/dt = 100A/μs	-	152	-	ns
Body Diode ReVerse RecoVery Charge	Q _{rr}		-	3.8	-	μC

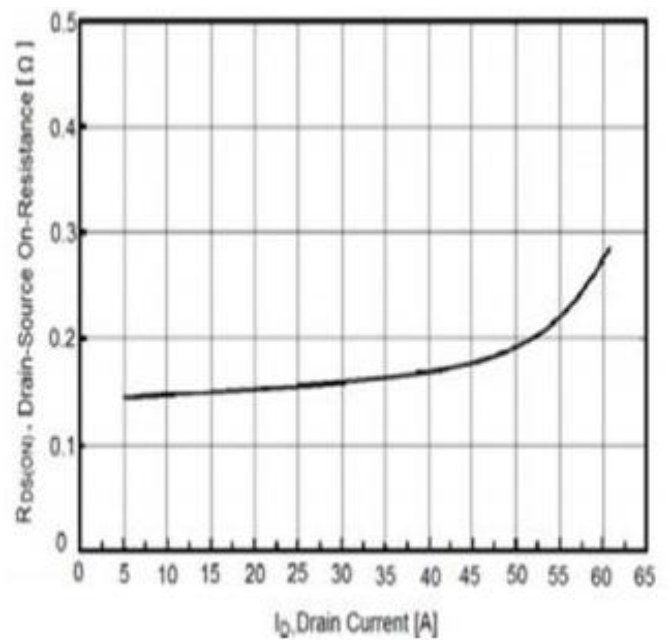
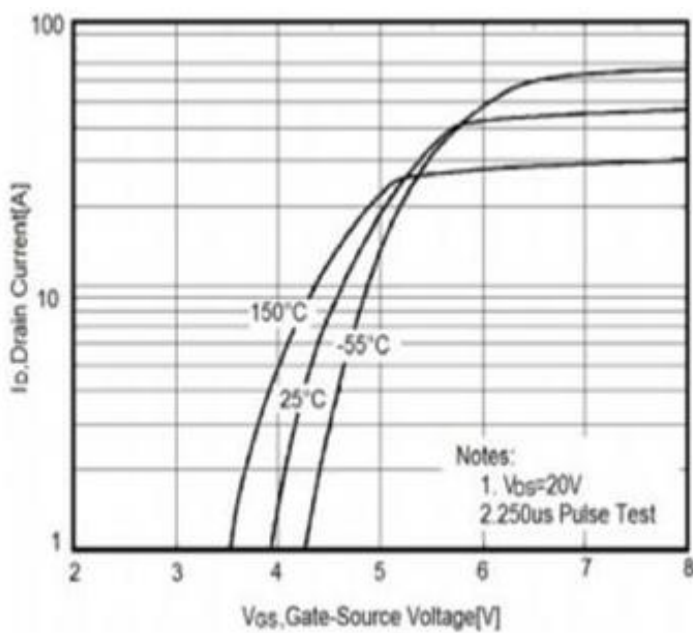
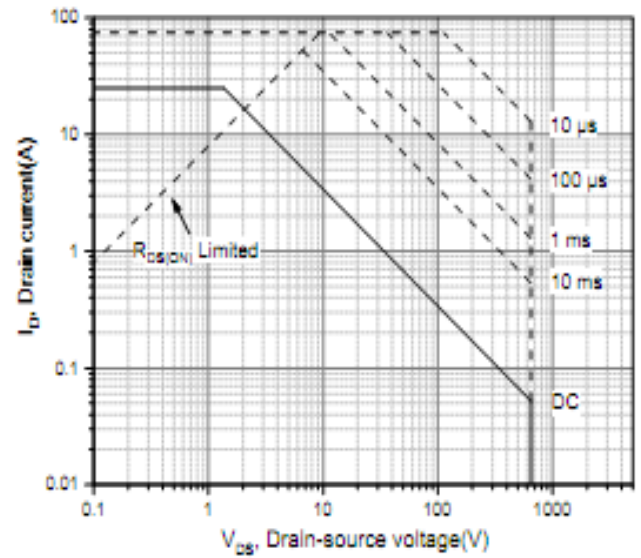
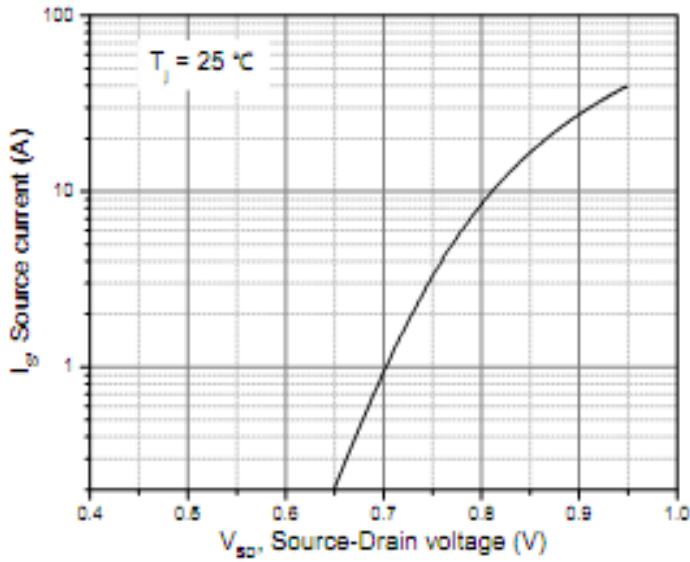
Note

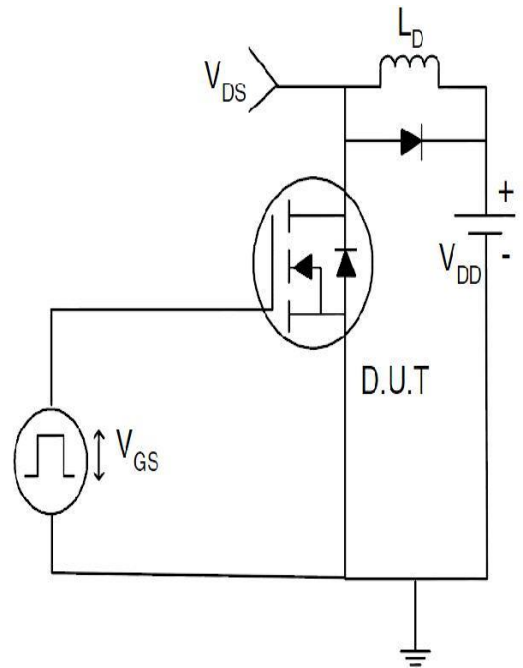
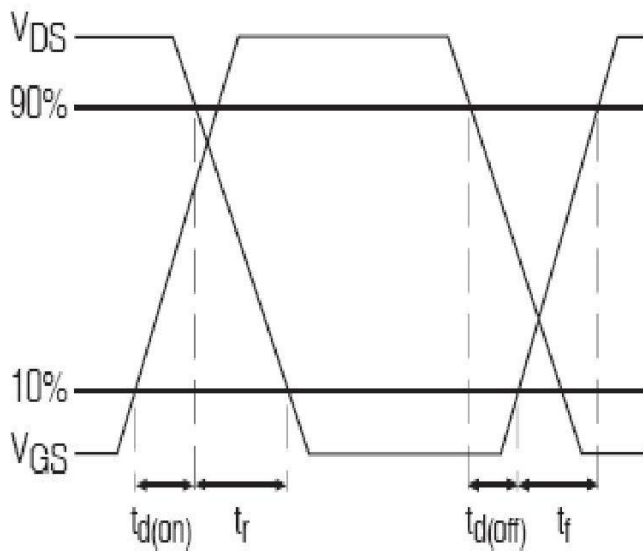
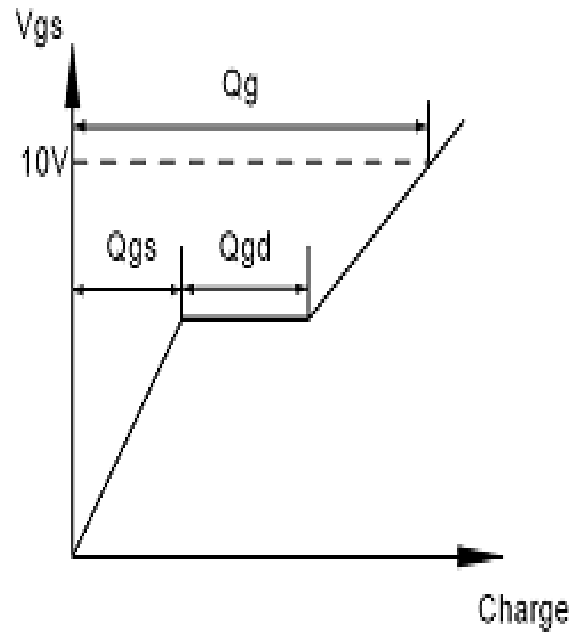
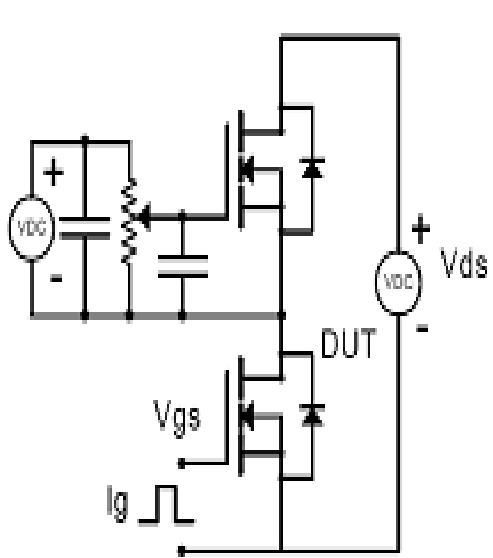
1. Surface mounted FR-4 board by JEDEC (jesd51-7)
2. Pulse width limited by T_{Jmax}
3. E_{AS} is tested at starting T_J = 25 °C, L = 1.0mH, I_{AS} = 30A, V_{GS} = 10V V_{DD} = 50V



Typical Characteristics (T_j=25C Noted)

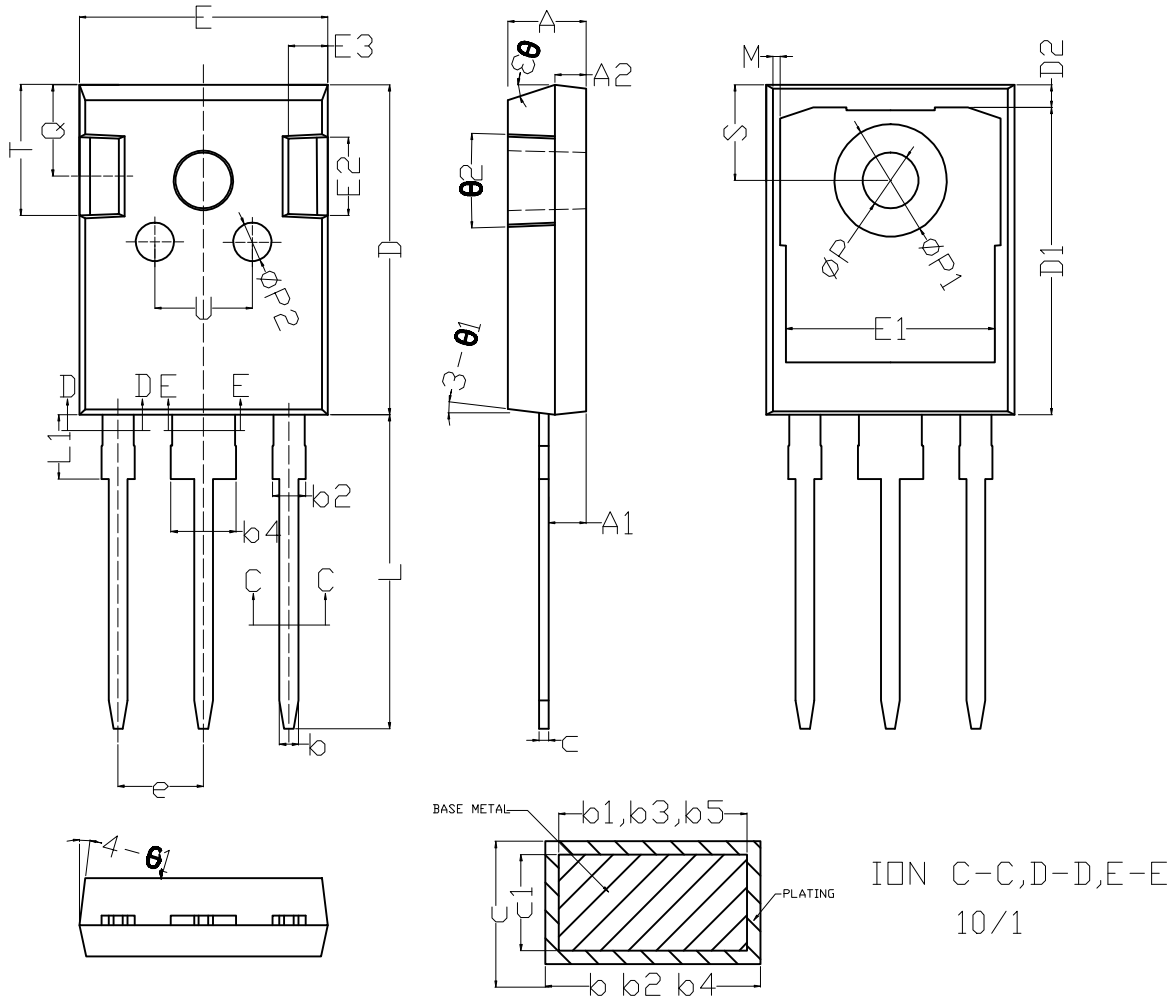








TO-247 Package Information



COMMON DIMENSIONS

SYMBOL	MIN	NDM	MAX
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16	1.21	1.26
b1	1.15	1.20	1.25
b2	1.95	2.10	2.15
b3	1.94	2.09	2.14
b4	3.10	3.15	3.20
b5	3.09	3.14	3.19
c	0.59	0.61	0.66
c1	0.58	0.60	0.65
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.44BSC		
L	19.80	19.92	20.10
L1	—	—	4.30
M	0.35	0.50	0.75
∅P	3.50	3.60	3.70
∅P1	7.00	7.20	7.40
∅P2	2.40	2.50	2.60
Q	5.60	5.80	6.00
S	6.05	6.15	6.25
T	9.80	10.00	10.20
U	6.00	—	6.40
∅1	5°	7°	9°
∅2	3°	5°	8°
∅3	13°	16°	19°